

Shenzhen Hengxunda Circuit Technology Co.,LTD

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Process Capability And Checking Parameters(Rigid PCB)

NO	ITEM	Technical Capabilities
1	Layers	1 Layer-38 Layer
2	Max.Board Size	1200mm*610mm /48"*24"
3	Finished Board Thickness	0.2mm--10.0mm / 0.008"--0.4"
4	Finished Copper Thickness	17um-420um / 0.5OZ--12OZ
5	Min.Trace Width/Space	0.075mm-0.065mm / 0.003"-0.0026"
6	Min.Hole Size	0.15mm / 0.006"
7	Hole Dim. Tolerance(PTH)	±0.05mm / ±0.002"
8	Hole Dim.Tolerance(NPTH)	±0.05mm / ±0.002"
9	Drill Location Tolerance	±0.05mm / ±0.002"
10	V-Cut Degrees	20-90 °C / 20DEG-90DEG
11	Min.V-Cut PCB Thickness	0.4mm / 0.016"
12	N/C Routing Tolerance	±0.1mm / ±0.004"
13	Min.Blind/Buried Via	0.15mm / 0.06"
14	Plug Hole Size	0.2mm--0.6mm / 0.008"--0.024"
15	Min.BGA PAD	0.2mm / 0.008"
16	Materials	FR4(TG130-TG170),Aluminium,Halogen-free, Rogers,ShengYi,KB,Guoji
17	Surface Finish	HASL-LF,ENIG,ImAg,ImSn,OSP,Gold plating, ENIG+OSP,HAL+G/F
18	Warp & Twist	≤0.75%
19	Electrical Testing	50--300V
20	Solderability Testing	245±5°C,3sec Wetting area least95%
21	Thermal Cycling Testing	288±5°C,10sec,3cycles
22	Ionic Contamination Testing	Pb,Hg,Cd,Cr(VI),PBB,PBDE six items are less than 1000ppm
23	Soldmask Adhesion Testing	260°C+/-5, 10S,3times